

SUBSTRATE FOR CIRCUIT WIRING

ABSTRACT OF THE DISCLOSURE

The present invention concerns a substrate for circuit wiring in which an electronic component is mounted, by soldering, to a wiring pattern formed on an insulated layer deposited over a metallic substrate. A silica-based filler and a rubber-based filler are added in the insulated layer to reduce the linear thermal expansion of the layer and increase its elastic modulus. The mounting portion of an electronic component is molded with a resin material to which a silica-based filler has been added, and which thus has a coefficient of linear thermal expansion smaller than the coefficient of linear thermal expansion of the insulated layer. This serves to alleviate the stress caused by the linear thermal expansion of the metallic substrate, and thereby to prevent separation from occurring between the insulated layer and the metallic substrate, as well as between the insulated layer and the wiring pattern, when subjected to a high-temperature environment.